

CMOS CAMERA MODULES



your BEST camera module partner

KLT-E7MA-OV5645 V2.1

OmniVision OV5645 MIPI Interfaccia Messa a fuoco automatica 5MP Modulo telecamera



| Modulo telecamera n. | KLT-E7MA-OV5645 V2.1 |
|---------------------------|--------------------------|
| Sensore d'immagine | OV5645 |
| EFL | 3.29 mm |
| F.NO | 2.8 |
| Pixel | 2592 x 1944 (QSXGA) |
| Vista ad angolo | 68.7° |
| Tipo di lente | 1/4 pollice |
| Dimensioni dell'obiettivo | 8.50 x 8.50 x 5.17 mm |
| Dimensione del modulo | 100.00 x 8.50 mm |
| Tipo di modulo | Messa a fuoco automatica |
| Interfaccia | MIPI |



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778



OV5645 5-megapixel product brief



High Quality 5-Megapixel Photography and HD Video for Low-Cost Mobile Devices



OmniVision's OV5645 is a high performance, 5-megapixel system-on-chip (SOC) ideally suited for the cost-sensitive segment of the mobile handset market. The CameraChip™ sensor's single MIPI port replaces both a bandwidth-limited DVP interface and a costly embedded JPEG compressor, allowing the new OV5645 sensor to save significant silicon area and cost. An embedded autofocus control with voice coil motor driver offers further cost savings for the end user, making the OV5645 a highly attractive alternative to other 5-megapixel sensors currently on the market.

The OV5645 also features a new picture-in-picture (PIP) architecture that offers an easy-to-implement, low-cost dual camera system solution for mobile handsets and smartphones. The feature is based on a master/slave configuration where a front-facing camera (OV7965) can be connected through the OV5645 master camera, enabling a two-camera system with PIP functionality without the need for an additional MIPI interface into the baseband processor.

Built on OmniVision's 1.4-micron OmniBSI™ pixel architecture, the OV5645 offers high performance 5-megapixel photography and 720p HD video at 60 frames per second (FPS) and 1080p HD video at 30 FPS with complete user control over formatting and output data transfer. The sensor's 720p HD video is captured in full field-of-view with 2 x 2 binning, which doubles the sensitivity and improves the signal-to-noise ratio (SNR). A unique post-binning, re-sampling filter function removes zigzag artifacts around slant edges and minimizes spatial artifacts to deliver even sharper, crisper color images.

Find out more at www.ovt.com.



Applications

- Cellular Phones
- PC Multimedia

■ Toys

■ Digital Still Cameras

Product Features

- 1.4 µm x 1.4 µm pixel with OmniBSI+™ technology for high performance (high sensitivity, low crosstalk, low noise, improved quantum efficiency)
- optical size of 1/4"
- automatic image control functions: automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), automatic 50/60 Hz luminance detection, and automatic blacklevel calibration (ABLC) udual lane MIPI output interface
- hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling
- support for output formats: RAW RGB, RGB565/555/444, YUV422/420, YCbCr422
- support for video or snapshot operations
- support for internal and external frame synchronization for frame exposure
- support for LED and flash strobe mode

- support for horizontal and vertical sub-sampling, binning
- support for minimizing artifacts on binned image
- support for data compression output
- support for anti-shake
- standard serial SCCB interface
- lacktriangle image quality controls: color saturation, lacktriangle embedded 1.5 V regulator for core
 - programmable I/O drive capability, I/O tri-state configurability
 - support for black sun cancellation
 - support for images sizes: 5 megapixel, and any arbitrary size scaling down from 5 megapixel
 - support for auto focus control (AFC) with embedded AF VCM driver
 - embedded microcontroller
 - suitable for module size of 8.5 x 8.5 x <6mm with both CSP and RW packaging

0V5645



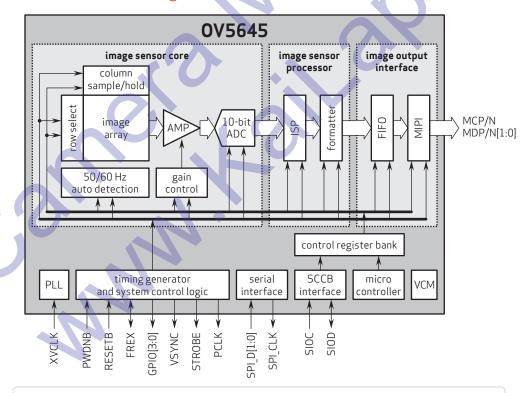
- 0V05645-A66A (color, lead-free, 66-pin CSP3)
- 0V05645-G04A (color, chip probing, 200 µm backgrinding, reconstructed wafer)

Product Specifications

- active array size: 2592 x 1944
- power supply: core: 1.5V ±5%
- (with embedded 1.5 regulator) analog: 2.6 3.0V (2.8V typical) I/O: 1.8V / 2.8V
- temperature range:
 operating: -30°C to 70°C junction
- temperature stable image: 0°C to 50°C junction temperature
- output formats: 8-/10-bit RGB RAW, RGB565/555/444, YUV422/420, YCbCr422 output
- lens size: 1/4"
- lens chief ray angle: 29.1°

- input clock frequency: 6 27 MHz
- max S/N ratio: 36 dB
- maximum image transfer rate: QSXGA (2592X1944): 15 fps
- -1080p: 30 fps
- 1280x960: 45 fps
- **720p**: 60 fps
- shutter: rolling shutter / frame exposure
- maximum exposure interval: 1964 x t_{ROW}
- pixel size: 1.4 μm x 1.4 μm
- image area: 3673.6 µm x 2738.4 µm
- package/die dimensions:
 CSP3: 6200 μm x 4860 μm
 COB: 6190 μm x 4850 μm

Functional Block Diagram



4275 Burton Drive Santa Clara, CA 95054

Tel: +1 408 567 3000 Fax: +1 408 567 3001 www.ovt.com

OmniVision reserves the right to make changes to their products or to discontinue any product or service without further notice. OmniVision, the OmniVision logo and OmniPixel are registered trademarks of DomniVision Technologies, Inc. OmniSSI is a trademark of OmniVision Technologies, Inc. All other trademarks are the property of their respective owners.

